

MA22D39

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Optimum for forward current (Effective value) $I_{F(RMS)} = 1.57$ A rectification
- Reverse voltage $V_R = 40$ V is guaranteed

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current (Effective value) *1	$I_{F(RMS)}$	1.57	A
Non-repetitive peak forward surge current *2	I_{FSM}	30	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code
Mini2-F1
- Pin Name
1: Anode
2: Cathode

■ Marking Symbol: 3N

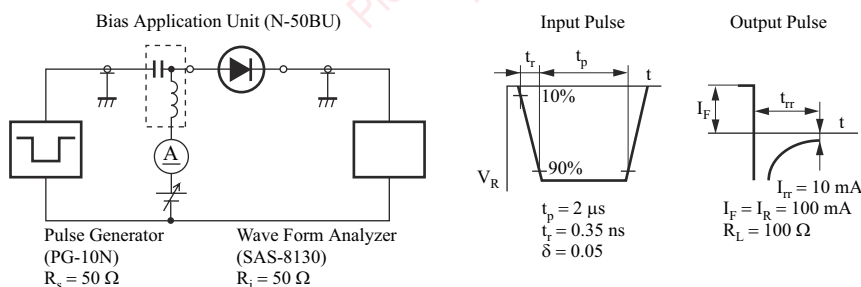
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

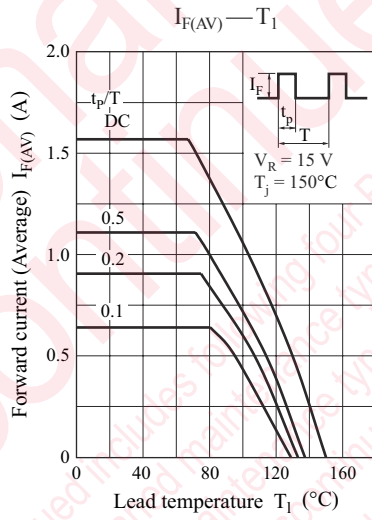
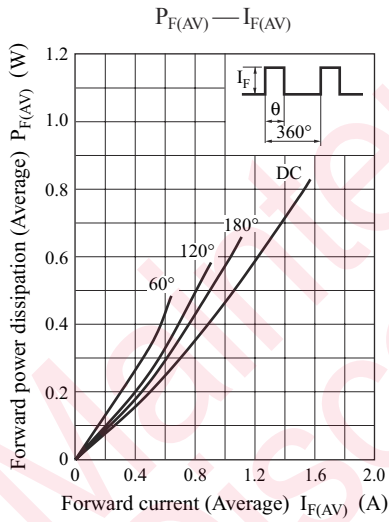
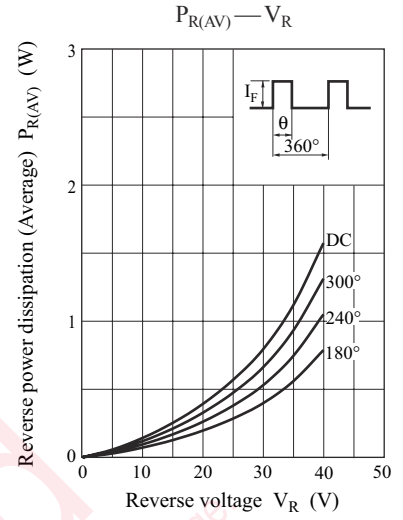
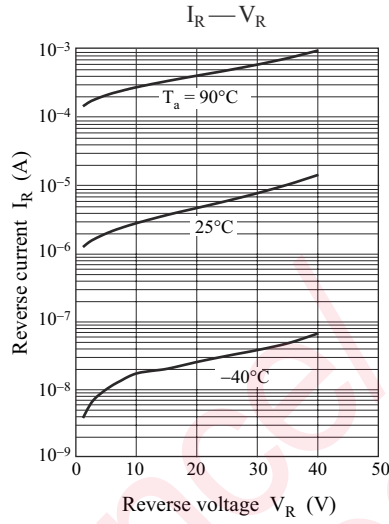
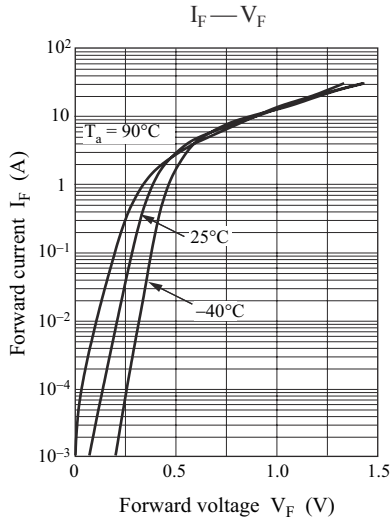
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 0.5$ A			0.48	V
	V_{F2}	$I_F = 1.1$ A			0.54	
	V_{F3}	$I_F = 1.5$ A			0.57	
Reverse current	I_R	$V_R = 40$ V			100	μA
Terminal capacitance	C_t	$V_R = 10$ V, $f = 1$ MHz		50		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA, $I_{rr} = 10$ mA, $R_L = 100 \Omega$		30		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

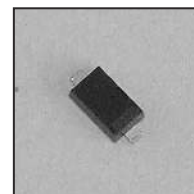
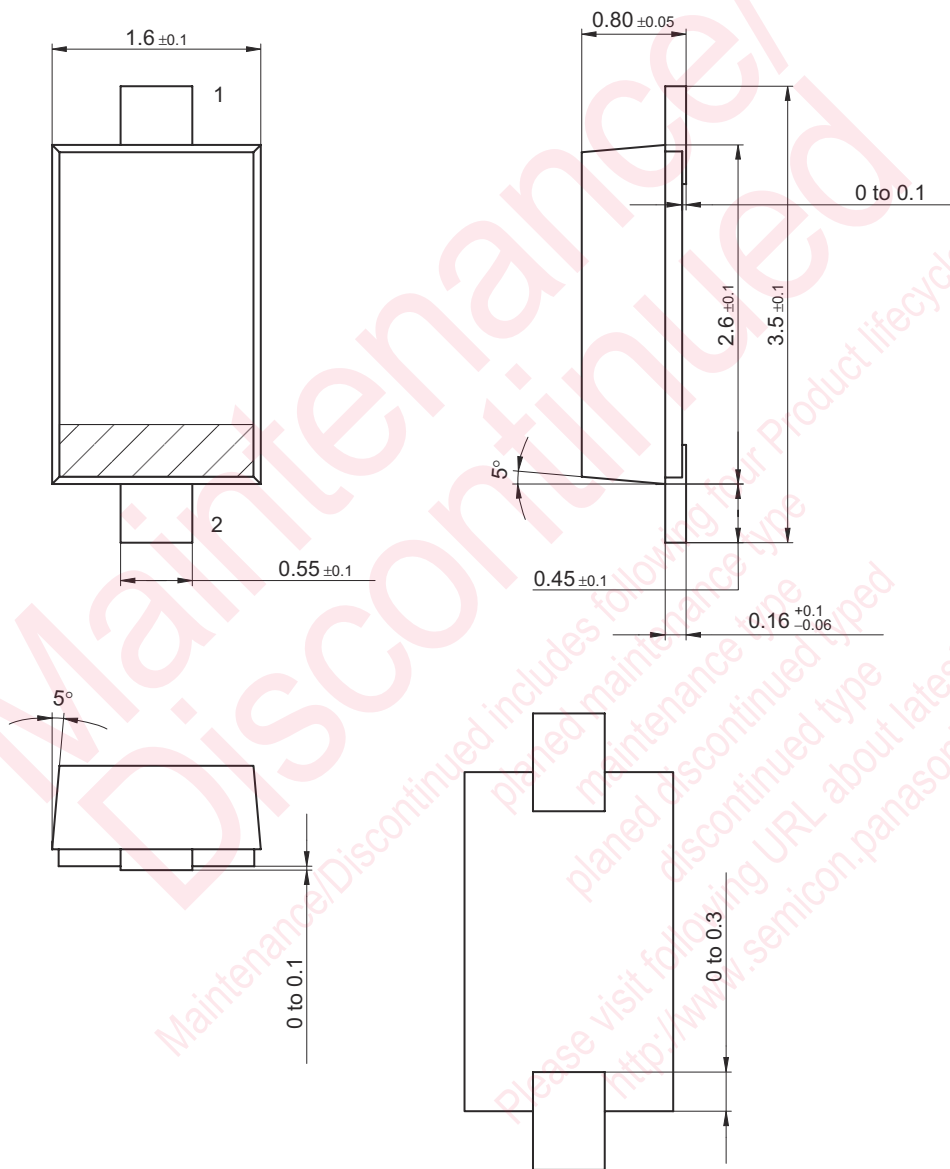
3. *: t_{rr} measurement circuit





Mini2-F1

Unit: mm



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